

PRODUCT SPECIFICATION

6223E-UUD

Wi-Fi Single-band 1x1 + Bluetooth4.2

USB Combo Module

Version:v1.0

Customer: _____

Customer P/N: _____

Signature: _____

Date: _____

Office: 14th floor, Block B, phoenix zhigu, Xixiang Street, Baoan District, Shenzhen

Factory: NO.8, Litong RD., Liuyang Economic & Technical Development Zone, Changsha, CHINA

TEL:+86-755-2955-8186

Website:www.fn-link.com

6223E-UUD Module Datasheet

Ordering Information	Part NO.	Description
	FG6223EUUD-W4	RTL8723DU b/g/n,Wi-Fi+BT4.2,1T1R,12.2X12.9mm, USB+PCM, Single antenna, PCB V3.0,(无 USB 落地电容)



CONTENTS

1. General Description	5
1.1 Introduction	5
1.2 Description	5
2. Features	6
3. Block Diagram	6
4. General Specification	7
4.1 WI-FI Specification	7
4.2 Bluetooth Specification	8
5. ID setting information	9
6. Pin Definition	9
6.1 Pin Outline	9
6.2 Pin Definition details	10
7. Electrical Specifications	10
7.1 Power Supply DC Characteristics	10
7.2 Power Consumption	11
7.3 Interface Circuit time series	11
7.3.1 module power-on&off time sequence	11
7.3.2 Timing information	13
7.3.3 Power Off by 3.3V power sequence	14
8. Size reference	15
8.1 Module Picture	15
8.2 Marking Description	16
8.3 List of certified information	17
8.4 Physical Dimensions	18
8.5 Layout Recommendation	19
9. The Key Material List	19
10. Reference Design	20
11. Recommended Reflow Profile	21
12. RoHS compliance	21
13. Package	22
13.1 Reel	22
13.2 Carrier Tape Detail	22
13.3 Packaging Detail	23
13.4 Tray	24
14. Moisture sensitivity	24

[illegible]

1. General Description

1.1 Introduction

6223E-UUD is a small size and low profile of Wi-Fi + BT Combo module, board size is 12.2mm*13mm . It can be easily manufactured on SMT process and highly suitable for tablet PC, ultra book, mobile device and consumer products. It provides USB interface for Wi-Fi and Bluetooth. The module provides simple legacy and 20MHz/40MHz co-existence mechanisms to ensure backward and network compatibility and Bluetooth can support BT2.1+EDR/BT3.0 and BT4.2.

6223E-UUD uses highly integrated Wi-Fi/BT single chip based on advanced COMS process. It's integrates whole Wi-Fi/BT function blocks into a chip, such as USB, MAC, BB, AFE, RFE, PA, EEPROM and LDO/SWR, except fewer passive components remained on PCB.

This compact module is a total solution for a combination of Wi-Fi + BT technologies. The module is specifically developed for Smart phones and Portable devices.

1.2 Description

Model Name	6223E-UUD
Product Description	Support Wi-Fi/Bluetooth functionalities
Dimension	L x W x H: 12.9 x 12.2 x1.8 mm (no shielding)
Wi-Fi Interface	Support USB2.0
BT Interface	Support USB2.0
OS supported	Android /Linux/ Windows
Operating temperature	0°C to 70°C
Storage temperature	-55°C to 85°C

2. Features

General Features

- Operate at ISM frequency bands (2.4GHz)
- IEEE standards support: IEEE 802.11b, IEEE 802.11g, IEEE 802.11n, IEEE 802.11d, IEEE 802.11e, IEEE 802.11h, IEEE 802.11i
- Enterprise level security which can apply WPA/WPA2 certification for Wi-Fi
- Wi-Fi 1 transmitter and 1 receiver allow data rates supporting up to 150 Mbps downstream and 150 Mbps upstream PHY rates

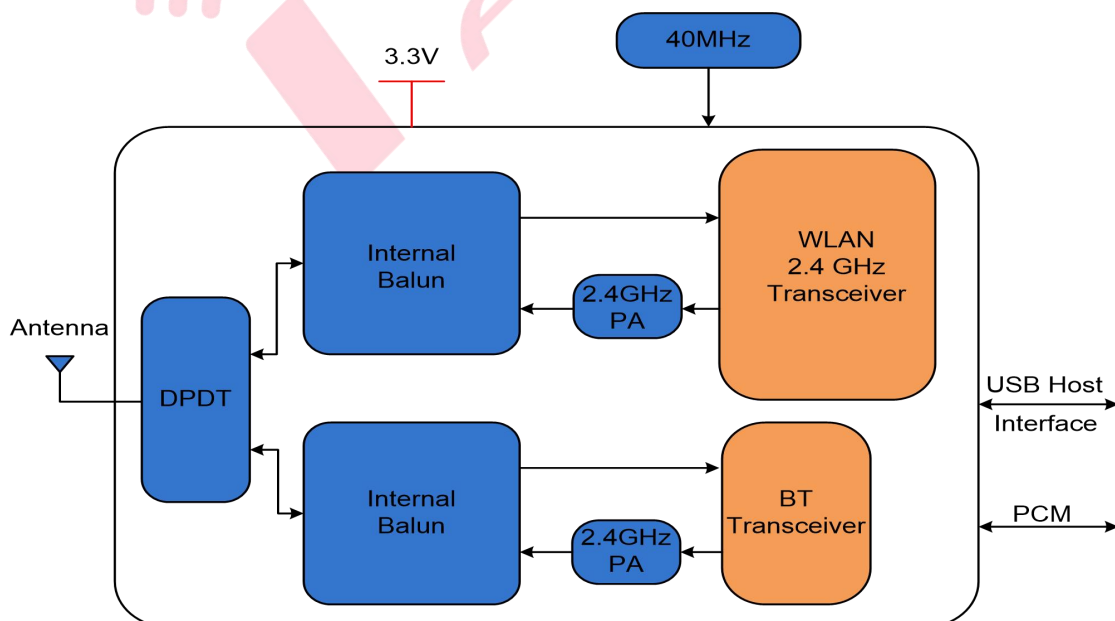
WLAN Interface

- USB for Wi-Fi and Bluetooth

Bluetooth Features

- Fully Qualified for Bluetooth 2.1+EDR specification including both 2Mbps and 3Mbps modulation mode
- Fully qualified for Bluetooth 3.0
- Fully qualified for Bluetooth 4.2 Dual mode
- Full – speed Bluetooth operation with Piconet and Scatternet support

3. Block Diagram



4. General Specification

4.1 WI-FI Specification

Feature	Description	
WLAN Standard	IEEE 802.11 b/g/n Wi-Fi compliant	
Frequency Range	2.400 GHz ~ 2.4835 GHz (2.4 GHz ISM Band)	
Number of Channels	2.4GHz: Ch1 ~ Ch14	
Test Items	Typical Value	EVM
Output Power	802.11b /11Mbps : 16dBm $\pm$ 2 dB	EVM $\leq$ -10dB
	802.11g /54Mbps : 14dBm $\pm$ 2 dB	EVM $\leq$ -25dB
	802.11n /MCS7 : 13dBm $\pm$ 2 dB	EVM $\leq$ -28dB
Spectrum Mask	Meet with IEEE standard	
Freq. Tolerance	$\pm$ 20ppm	
Test Items	TYP Test Value	Standard Value
SISO Receive Sensitivity (11b,20MHz) @8% PER	- 1Mbps PER @ -91 dBm	$\leq$ -83
	- 2Mbps PER @ -89 dBm	$\leq$ -80
	- 5.5Mbps PER @ -87 dBm	$\leq$ -79
	- 11Mbps PER @ -85 dBm	$\leq$ -76
SISO Receive Sensitivity (11g,20MHz) @10% PER	- 6Mbps PER @ -87 dBm	$\leq$ -85
	- 9Mbps PER @ -86 dBm	$\leq$ -84
	- 12Mbps PER @ -84 dBm	$\leq$ -82
	- 18Mbps PER @ -82 dBm	$\leq$ -80
	- 24Mbps PER @ -79 dBm	$\leq$ -77
	- 36Mbps PER @ -75 dBm	$\leq$ -73
	- 48Mbps PER @ -71 dBm	$\leq$ -69
	- 54Mbps PER @ -70 dBm	$\leq$ -68
SISO Receive Sensitivity (11n,20MHz) @10% PER	- MCS=0 PER @ -87 dBm	$\leq$ -85
	- MCS=1 PER @ -84 dBm	$\leq$ -82
	- MCS=2 PER @ -82 dBm	$\leq$ -80
	- MCS=3 PER @ -79 dBm	$\leq$ -77
	- MCS=4 PER @ -75 dBm	$\leq$ -73
	- MCS=5 PER @ -71 dBm	$\leq$ -69
	- MCS=6 PER @ -70 dBm	$\leq$ -68
	- MCS=7 PER @ -69 dBm	$\leq$ -67
SISO Receive Sensitivity (11n,40MHz) @10% PER	- MCS=0, PER @ -84 dBm	$\leq$ -82
	- MCS=1, PER @ -81 dBm	$\leq$ -79

	- MCS=2, PER @ -79 dBm	≤ -77
	- MCS=3, PER @ -76 dBm	≤ -74
	- MCS=4, PER @ -72 dBm	≤ -70
	- MCS=5, PER @ -68 dBm	≤ -66
	- MCS=6, PER @ -67 dBm	≤ -65
	- MCS=7, PER @ -66 dBm	≤ -64
Maximum Input Level	802.11b : ≥ -8 dBm	
	802.11g/n : ≥ -20 dBm	

4.2 Bluetooth Specification

Feature	Description
General Specification	
Bluetooth Standard	BDR,EDR(1Mbps & 2Mbps & 3Mbps),LE(1Mbps)
Host Interface	USB
Frequency Band	2400 MHz ~ 2483.5 MHz
Number of Channels	79 channels for classic,40 channels for BLE
Modulation	GFSK, $\pi/4$ -DQPSK,8DPSK
RF Specification	
Output Power , tolerance ± 3 dB	
	CL1(dBm)
BDR Output Power	5
EDR Output Power	5
BLE Output Power	5
Sensitivity, tolerance : /	
Sensitivity @ BER=0.1% for GFSK (1Mbps)	-89
Sensitivity @ BER=0.01% for $\pi/4$ -DQPSK (2Mbps)	-86
Sensitivity @ BER=0.01% for 8DPSK (3Mbps)	-83

Sensitivity @ BLE=30.8% for LE (1Mbps)	-89
Maximum Input Level	GFSK (1Mbps):-20dBm
	$\pi/4$ -DQPSK (2Mbps) :-20dBm
	8DPSK (3Mbps) :-20dBm

5. ID setting information

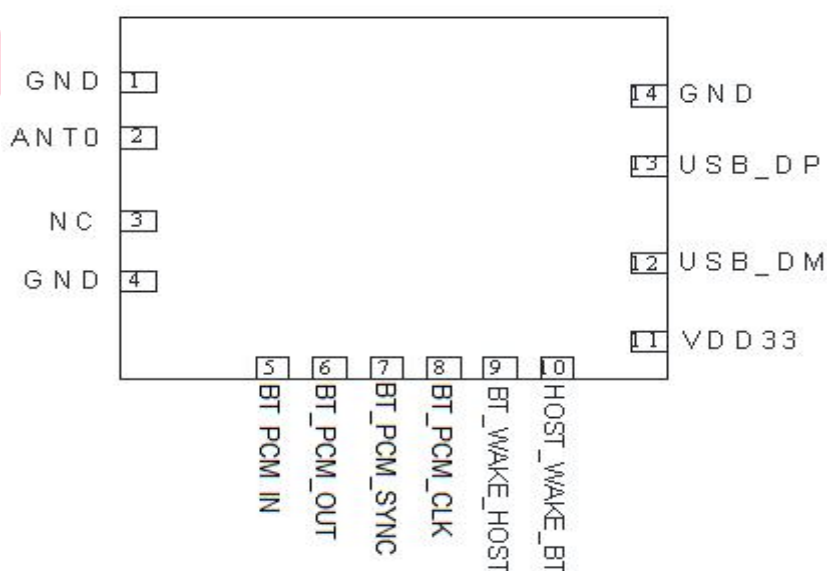
WI-FI

Vendor ID	0BDAh
Product ID	D723h

6. Pin Definition

6.1 Pin Outline

< TOP VIEW >



6.2 Pin Definition details

NO.	Name	Type	Description	Voltage
1	GND	—	Ground connections	
2	ANT 0	I/O	RF I/O	
3	NC	I/O	Floating (NC)	
4	GND	—	Ground connections	
5	BT_PCM_IN	I/O	BT_PCM_IN. If not used please NC, Don' t connected to ground.	3.3V
6	BT_PCM_OUT	I/O	BT_PCM_OUT. If not used please NC, Don' t connected to ground.	3.3V
7	BT_PCM_SYNC	I/O	BT_PCM_SYNC. If not used please NC, Don' t connected to ground.	3.3V
8	BT_PCM_CLK	I/O	BT_PCM_CLK. If not used please NC, Don' t connected to ground.	3.3V
9	BT_WAKE_HOST	O	Bluetooth device wake up host IC pin GPIO14, pull high boot to test mode. pull low boot to normal mode. be careful to using this pin.	3.3V
10	HOST_WAKE_BT	I	Host wake up Bluetooth device IC pin GPIO13	3.3V
11	VDD33	—	Main power voltage source input 3.3V	3.3V
12	USB_DM	I/O	USB2.0 differential pair for WLAN And Bluetooth	
13	USB_DP	I/O	USB2.0 differential pair for WLAN And Bluetooth	
14	GND	—	Ground connections	

P:POWER I:INPUT O:OUTPUT

7. Electrical Specifications

7.1 Power Supply DC Characteristics

	MIN	TYP	MAX	Unit
--	-----	-----	-----	------

Operating Temperature	0	25	70	deg.C
VCC33	3.0	3.3	3.6	V
ESD	3.5			KV

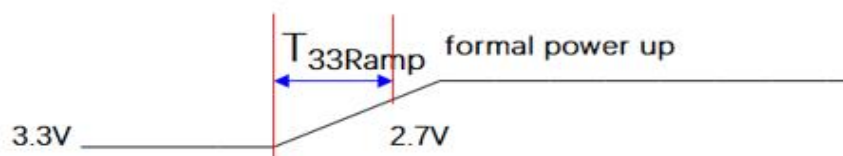
7.2 Power Consumption

Power Consumption		VCC33 = 3.3V(Unit:mA)
	Wi-Fi on Mode	68
	TX (2.4G HT40)	110
	RX (2.4G HT40)	107
	BT on	8.5

7.3 Interface Circuit time series

7.3.1 module power-on&off time sequence

	Min	Typical	Max	Unit
T33 power on ramp	0.2	0.5	2.5	ms
T33 power off ramp	0.2	5	10	ms



1.上下电时序请满足表格要求；

The power up ramp and power down ramp must meet the following table.

2.上下电过程如有较长时间中间电压停留都会有几率导致 efuse 被窜写；

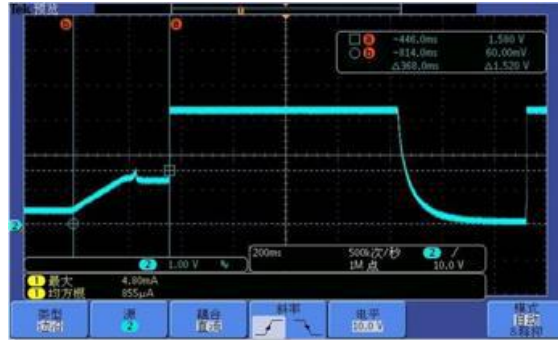
If climbing process for a long time during power-on and power-off , It may cause efuse to be overwritten.

3.建议主芯片上电完成后，再给模组上电；

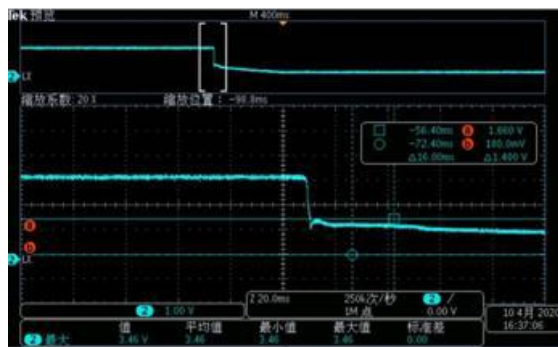
it is recommended to power on the module after platform side.

4.如有下图所示异常上下电时序，务必做相应调整符合时序规格；

If power on/off timing as below shown, must modify to meet the timing specification.

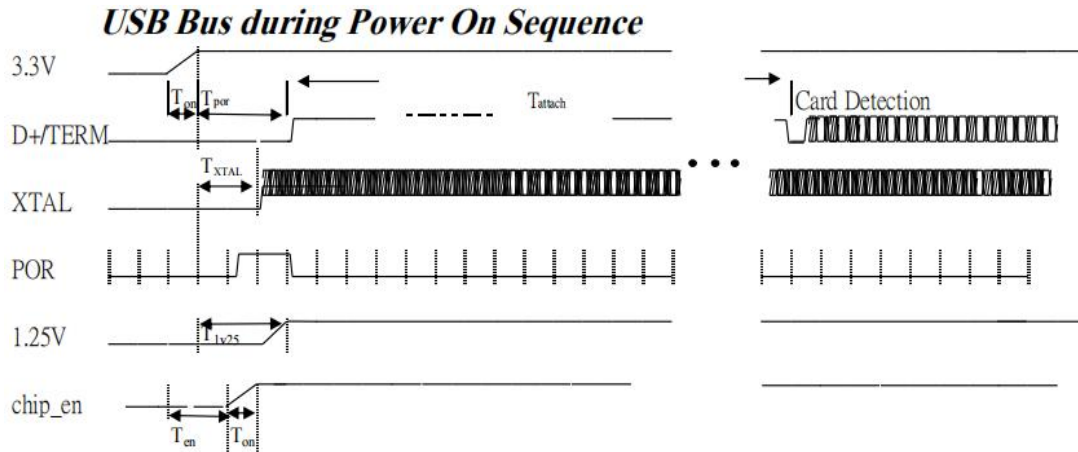


异常上电时序



异常下电时序

7.3.2 Timing information



RTL8723DU USB Bus Power On Sequence

T_{on}: The main power ramp up duration

T_{por}: The power on reset releases and power management unit executes power on tasks

T_{attach}: USB attach state

T_{k-state}: the duration from register attached to USB host starting card detection procedure

The power on flow description:

After main 3.3V ramp up, the internal power on reset is released by power ready detection circuit and the power management unit will be enabled. The power management unit enables the internal regulator and clock circuits.

The power management unit also enables the USB circuits.

USB analog circuits attach resistors to indicate the insertion of the USB device

The typical timing range

	Unit	Min	Typical	Max
T_{on}	ms	0.2	1.5	5
T_{por}	ms	--	2	10
T_{xtal}	ms	--	1.5	8
T_{attach}	ms	100	250	--
T_{lv25}	ms	-	2	5
T_{en}	ms	0	0	5

PCM Interface Characteristics

The RTL8723D supports a PCM digital audio interface that is used for transmitting digital audio/voice data to/from the Audio Codec. Features are supported as below:

- Supports Master and Slave mode
- Programmable long/short Frame Sync
- Supports 8-bit/16-bit linear PCM formats
- PCM Master Clock Output: 64, 128, 256, or 512kHz
- Supports SCO/ESCO link

PCM Format

FrameSync is the synchronizing function used to control the transfer of DAC_Data and ADC_Data. A Long FrameSync indicates the start of ADC_Data at the rising edge of FrameSync (Figure 7. Long FrameSync), and a Short FrameSync indicates the start of ADC_Data at the falling edge of FrameSync (Figure 8. Short FrameSync).

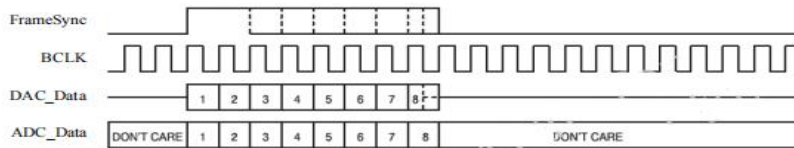


Figure 7. Long FrameSync

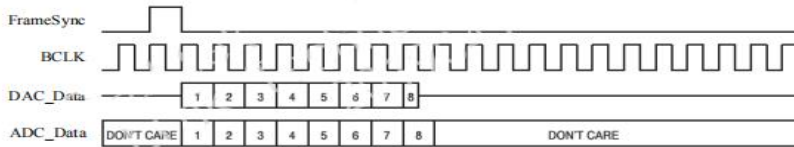
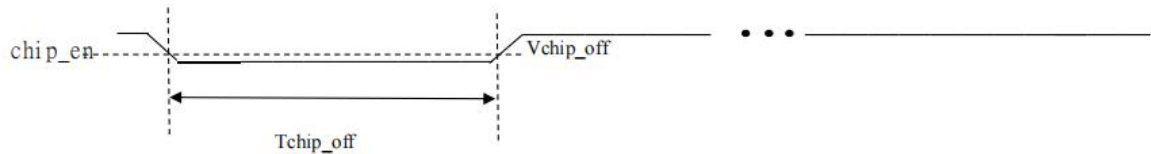


Figure 8. Short FrameSync

7.3.3 Power Off by 3.3V power sequence

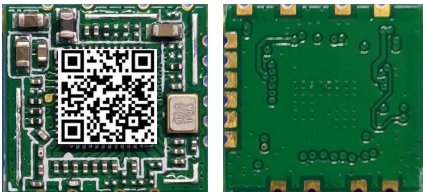
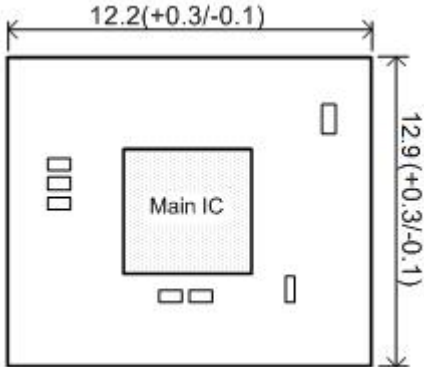


	Min	Typical	Max	Unit	Description
T_{chip_off}	10	100	--	ms	Chip_en reset time
V_{chip_off}	--	--	0.4	V	Chip_en reset voltage

When chip_en reset and on afterward, the voltage of chip_en must keep lower than Vchip_off, and the chip_en keeping off duration must be more than Tchip_off.

8. Size reference

8.1 Module Picture

L x W : 12.9 x 12.2 (+0.3/-0.1) mm 	
No shielding H: 1.8 (±0.2) mm	
Weight	0.51g

8.2 Marking Description



贴纸尺寸: 5*5mm
二维码尺寸: 4*4mm
红点不需打印, 为芯片极性点

标贴尺寸: 耐高温二维码标签贴纸, 5X5mm(单排贴纸)

备注:

1. 二维码: 编码规则为“wifimac 地址;成品料号”

例如: 112233445566;FG6223EUUD-W4 (MAC 地址以实际为准)。

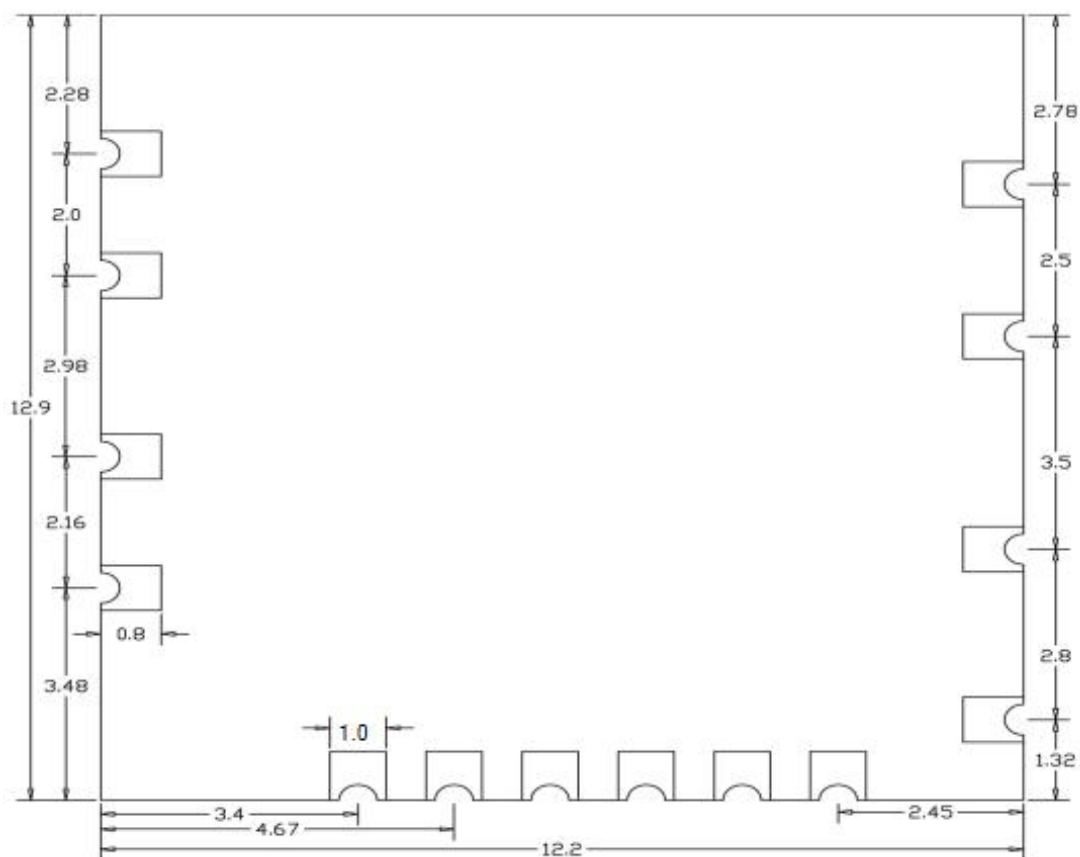
---BTMAC 在 WIFIMAC 基础上+1 (WIFI 地址需跳 1, 不能与 BT 地址重复) 二维码中不 显示此内容。

8.3 List of certified information

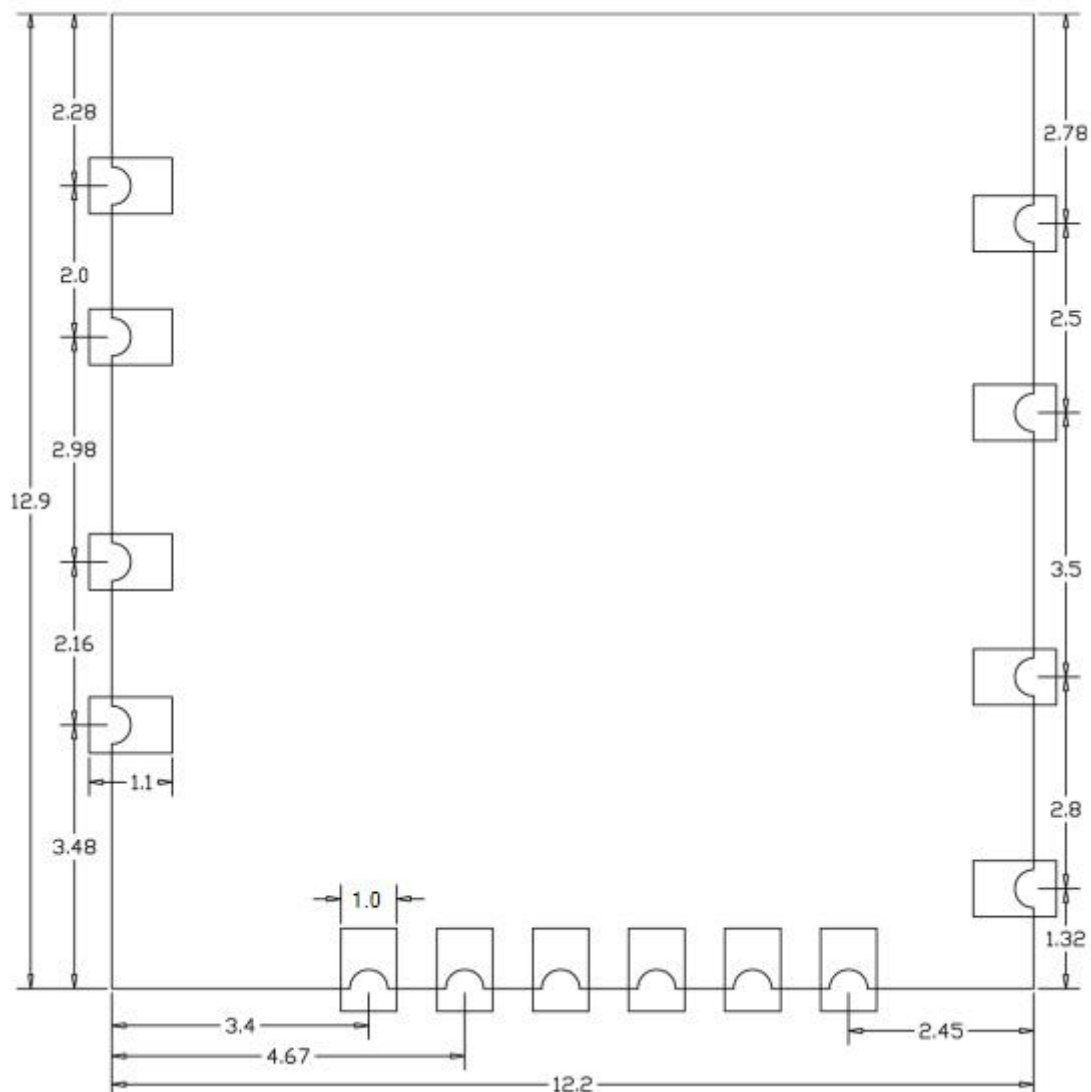
Certification project	Certificate number
SRRC	CMIIT ID:2019DP4145(M)
FCC	2AATL-6223E-UUD
CE	0370-RED-4546
IC	TBD
NCC	TBD
KCC	TBD
TELEC	TBD
Brazil	TBD
Argentina	TBD
Japan	TBD
BQB	D039512

8.4 Physical Dimensions

<TOP View>



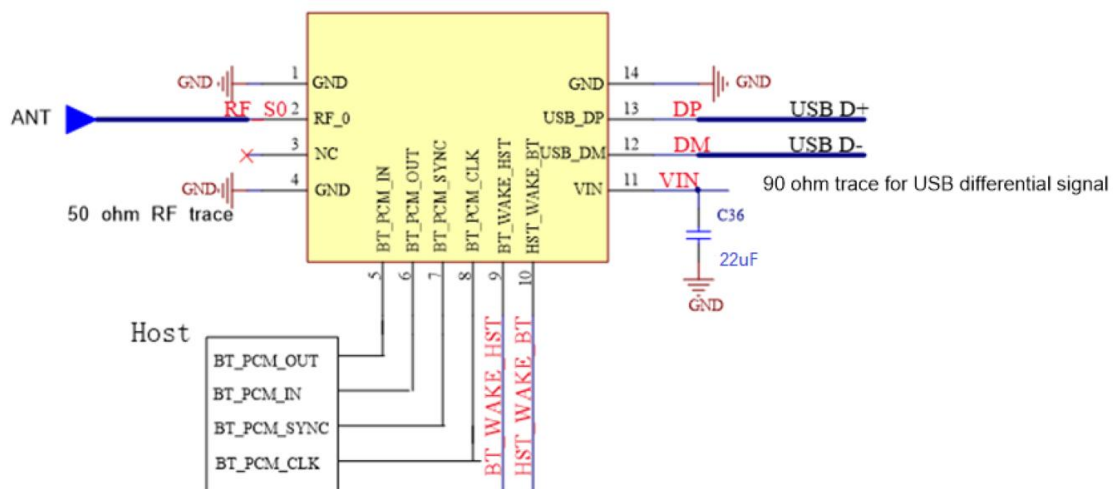
8.5 Layout Recommendation



9. The Key Material List

Item	Part Name	Description	Manufacturer
1	Crystal	2520 40MHz 15pF 10ppm	ECEC, TKD, Hosonic, JWT, TXC
2	Chipset	RTL8723DU-CG	Realtek
3	PCB	6223E-UUD-V3.0	XY-PCB,GDKX,Sunlord,SLPCB,Truly
4	TVS	0201 4V 0.05pF 15KV TVS	Murata,Sunlord,Wayon,JieJie Microelectronics
5	Inductor	2.2uH±20%, 0.60A, 0.560ohm	Sunlord,Ceaiya,cenke,Jinkai,microgate

10. Reference Design



Note:

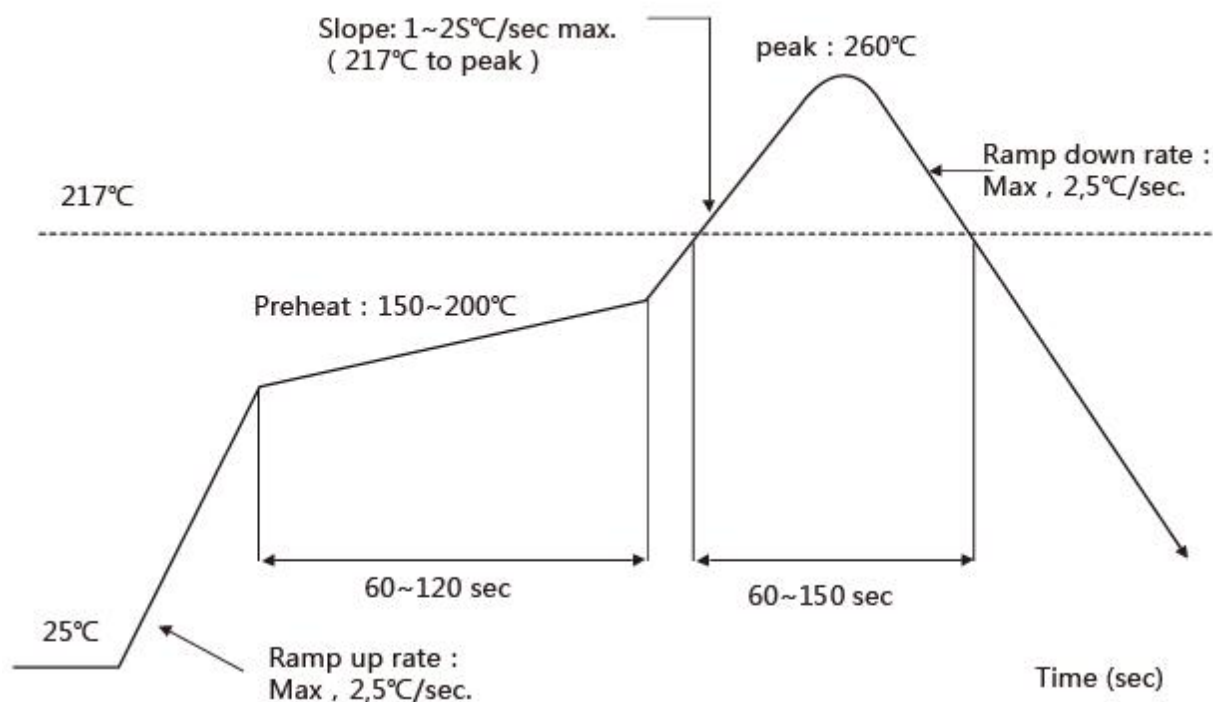
1. Please add 22uF cap for VCC_3V3.
2. For USB 2.0 differential signal, requires 90 ohm impedance.
3. For PIN2 and PIN3 RF IO trace, keep 50 ohm impedance.

11. Recommended Reflow Profile

Referred to IPC/JEDEC standard.

Peak Temperature : $<260^{\circ}\text{C}$

Number of Times : ≤ 2 times



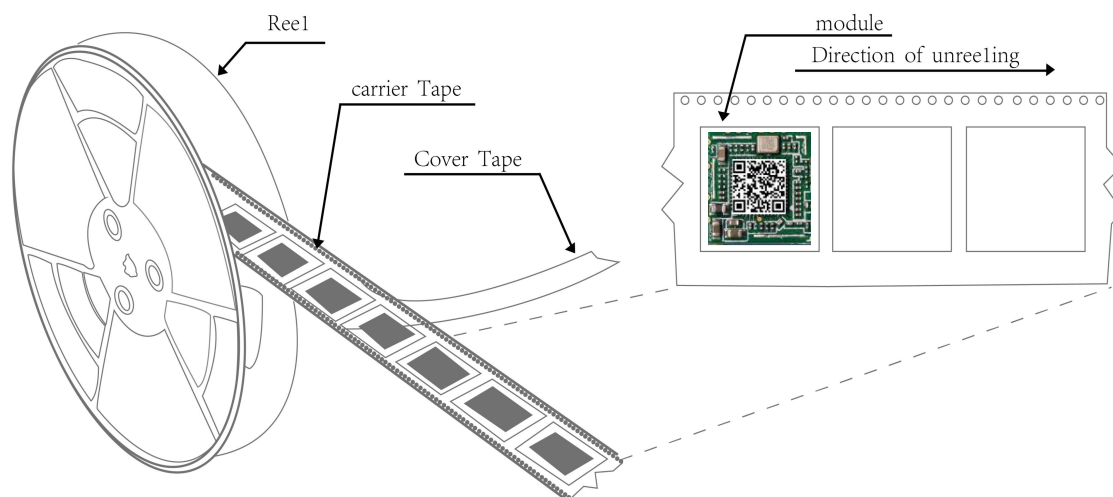
12. RoHS compliance

All hardware components are fully compliant with EU RoHS directive

13. Package

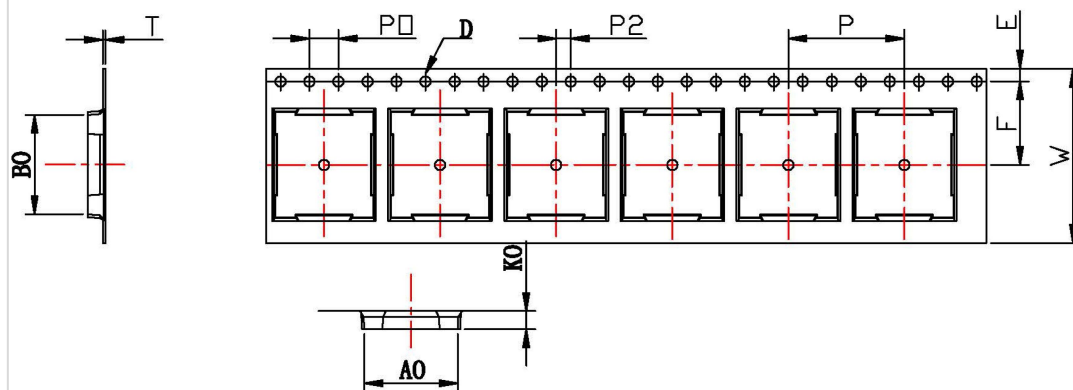
13.1 Reel

A roll of 1500pcs



13.2 Carrier Tape Detail

ITEM	W	A0	B0	D	F	E	K0	P0	P2	P	T
DIM	24	12.50	13.35	1.50	11.5	1.75	2.5	4.0	2.0	16.0	0.30
TOLE	$\begin{smallmatrix} +0.3 \\ -0.3 \end{smallmatrix}$	± 0.15	± 0.15	$\begin{smallmatrix} +0.1 \\ -0.0 \end{smallmatrix}$	$\begin{smallmatrix} +0.1 \\ -0.1 \end{smallmatrix}$	± 0.1	± 0.10	± 0.1	± 0.1	± 0.1	± 0.05



13.3 Packaging Detail

the take-up package



Using self-adhesive tape

Size of black tape: 24mm*32.6m the cover tape :21.3mm*32.6m

Color of plastic disc: blue



NY bag size:450*415mm



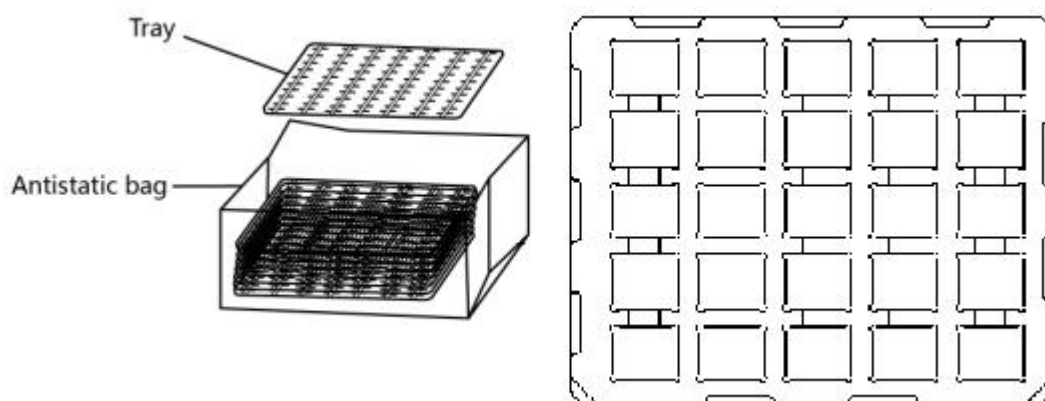
size : 350*350*35mm



The packing case size:360*210*370mm

13.4 Tray

Use pallet packaging for less than 300 pieces



14. Moisture sensitivity

The Modules is a Moisture Sensitive Device level 3, in according with standard IPC/JEDEC J-STD-020, take care

all the relatives requirements for using this kind of components.

Moreover, the customer has to take care of the following conditions:

- Calculated shelf life in sealed bag: 12 months at $<40^{\circ}\text{C}$ and $<90\%$ relative humidity (RH)
- Environmental condition during the production: 30°C / 60% RH according to IPC/JEDEC J-STD-033A paragraph 5
- The maximum time between the opening of the sealed bag and the reflow process must be 168 hours if condition
- “IPC/JEDEC J-STD-033A paragraph 5.2” is respected
- Baking is required if conditions b) or c) are not respected
- Baking is required if the humidity indicator inside the bag indicates 10% RH or more